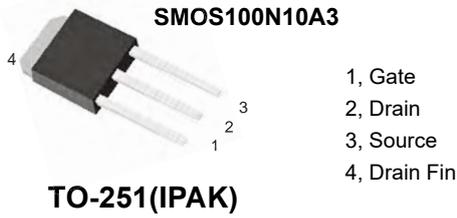


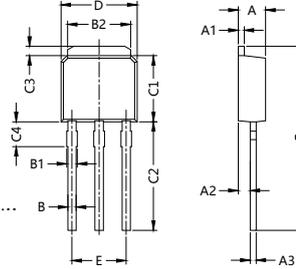
# SMOS100N10A3 SMOS100N10A4

## N Channel Power MOSFETs

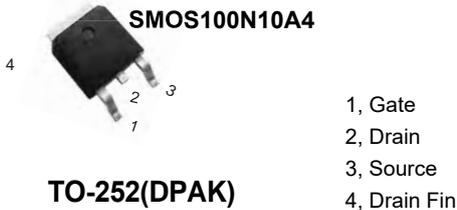


- 1, Gate
- 2, Drain
- 3, Source
- 4, Drain Fin

### Dimensions TO-251

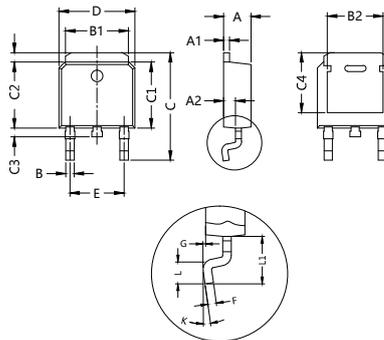


Dim.	Millimeter		Dim.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.20	2.40	C	14.50	15.80
A1	0.40	0.60	C1	5.85	6.20
A2	0.70	1.30	C2	7.85	8.60
A3	0.45	0.60	C3	0.60	1.20
B	0.50	0.80	C4	1.75	2.30
B1	0.65	1.00	D	6.30	6.70
B2	5.20	5.50	E	4.40	4.60

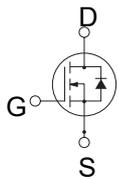


- 1, Gate
- 2, Drain
- 3, Source
- 4, Drain Fin

### Dimensions TO-252



Dim.	Millimeter	
	Min.	Max.
A	2.20	2.40
A1	0.40	0.60
A2	0.90	1.25
B	0.60	1.00
B1	5.20	5.50
B2	4.80	5.20
C	9.50	10.20
C1	5.90	6.20
C2	1.00	1.30
C3	0.60	1.00
C4	5.25	5.95
D	6.40	6.70
E	4.40	4.60
F	0.45	0.60
G	0.03	0.23
K	0°	8°
L	1.00	/
L1	2.80	3.25



G=Gate  
D=Drain  
S=Source

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	$I_{D25}$	100	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	$I_{D100}$	70	A
Pulsed Drain Current	$I_{DM}$	265	A
Maximum Power Dissipation	TO-251	$P_D$	121 W
	TO-252	$P_D$	120 W
Single pulse avalanche energy (Note 5)	$E_{AS}$	126	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ\text{C}$

### Thermal Characteristic

Thermal Resistance, Junction-to-Case (TO-251)	Max	$R_{\theta JC}$	1.20	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case (TO-252)	Max	$R_{\theta JC}$	1.25	$^\circ\text{C/W}$



# SMOS100N10A3 SMOS100N10A4

## N Channel Power MOSFETs

### Electrical Characteristics

(T<sub>J</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	-	5.4	6.6	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	-	110	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, F=1.0MHz	-	2600	-	PF
Output Capacitance	C <sub>oss</sub>		-	565	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	9.0	-	PF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, F=1.0MHz	-	1.7	-	Ω
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =75V, I <sub>D</sub> =20A V <sub>GS</sub> =10V, R <sub>G</sub> =5.8Ω	-	11	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	17.6	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	46	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	34	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =75V, I <sub>D</sub> =20A V <sub>GS</sub> =10V	-	45	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	27	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	9.7	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A	-	0.72	1.1	V
Diode Forward Current (Note 2)	I <sub>S</sub>	T <sub>J</sub> =25°C, I <sub>F</sub> =20A	-	-	120	A
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt=100A/μs (Note 3)	-	46	-	uC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, L=0.4mH, R<sub>g</sub>=25Ω

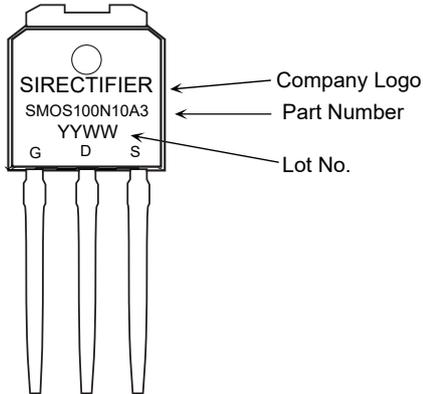


# SMOS100N10A3 SMOS100N10A4

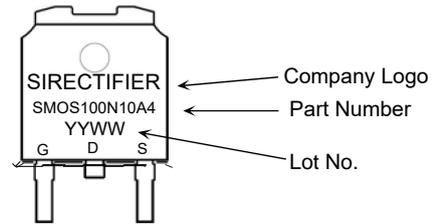
## N Channel Power MOSFETs

### Marking

**SMOS100N10A3**  
(TO-251)



**SMOS100N10A4**  
(TO-252)

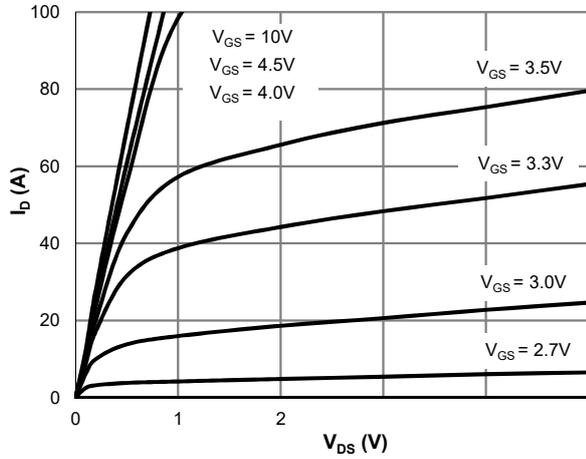


### Ordering Information

Part Number	Package	Shipping	Marking Code
SMOS100N10A3	TO-251	50pcs / Tube	SMOS100N10A3
SMOS100N10A4	TO-252	1000pcs / Tape & Reel	SMOS100N10A4

# SMOS100N10A3 SMOS100N10A4

## N Channel Power MOSFETs



Saturation Characteristics

Figure.1 Typical Output Characteristics

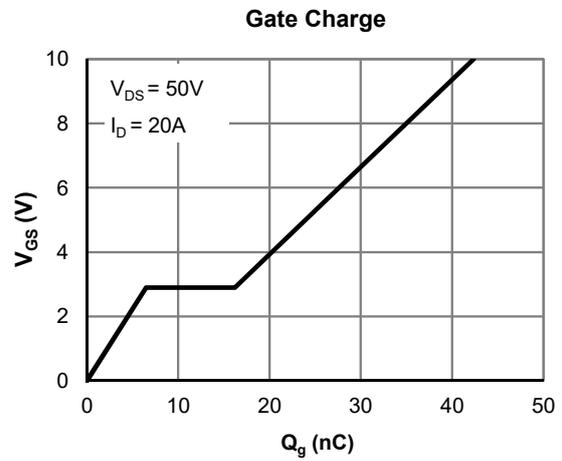
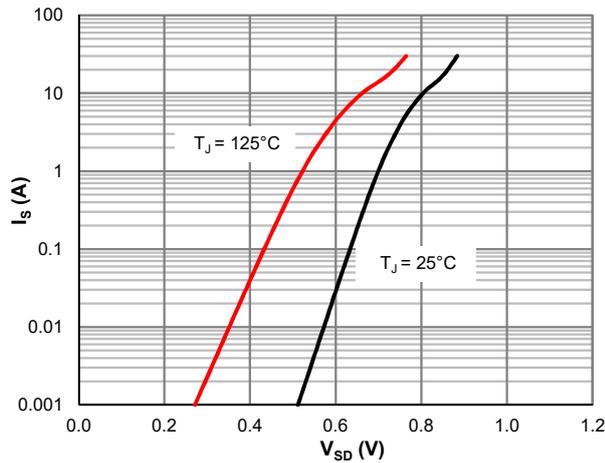
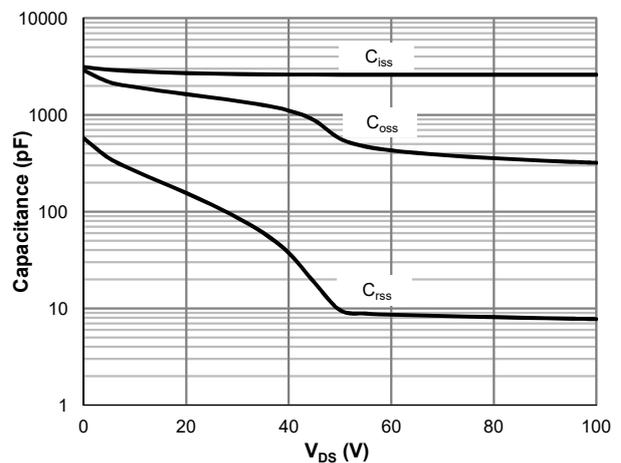


Figure.2 Typical Gate Charge vs Gate to Source Voltage



Body-Diode Characteristics

Figure.3 Typical Body Diode Transfer Characteristics



Capacitance Characteristics

Figure.4 Typical Capacitance vs Drain to Source Voltage

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## N Channel Power MOSFETs

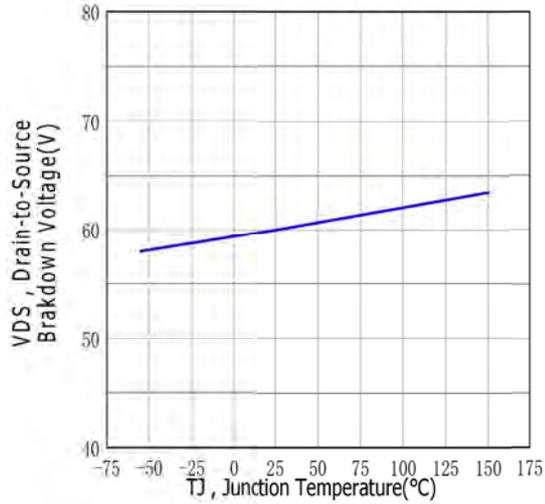


Figure.5 Typical Breakdown Voltage vs Junction Temperature

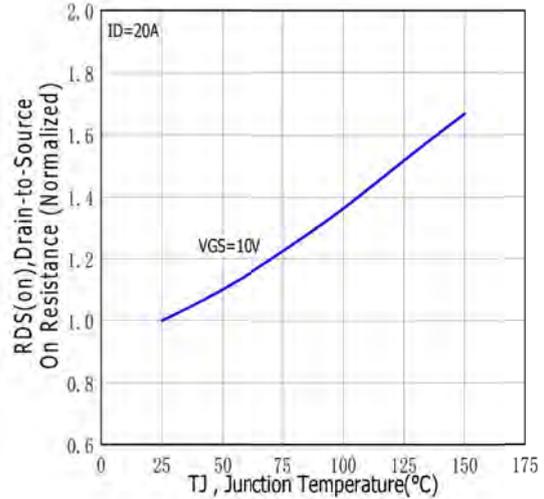


Figure.6 Typical Drain to Source on Resistance vs Junction Temperature

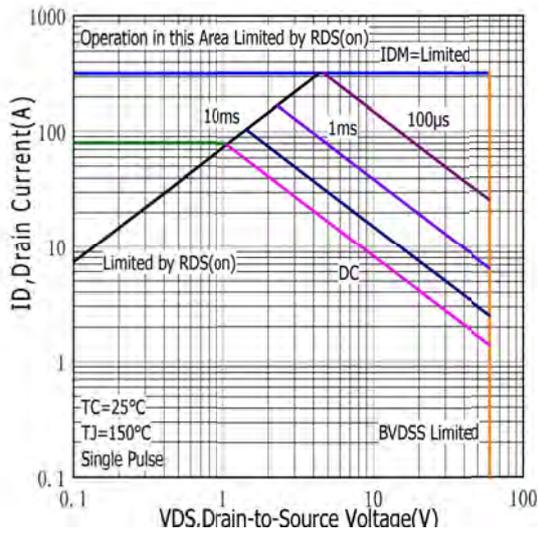


Figure.7 Maximum Forward Bias Safe Operating Area

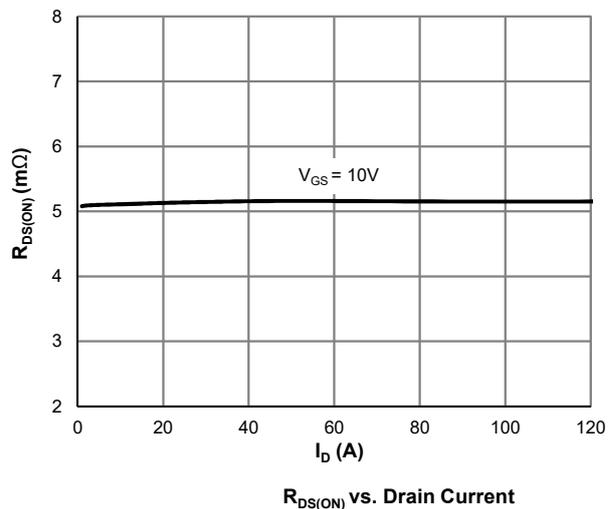


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

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## N Channel Power MOSFETs

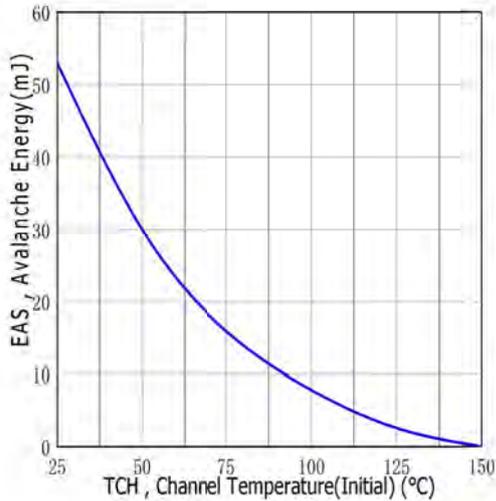


Figure.9 Maximum EAS vs Channel Temperature

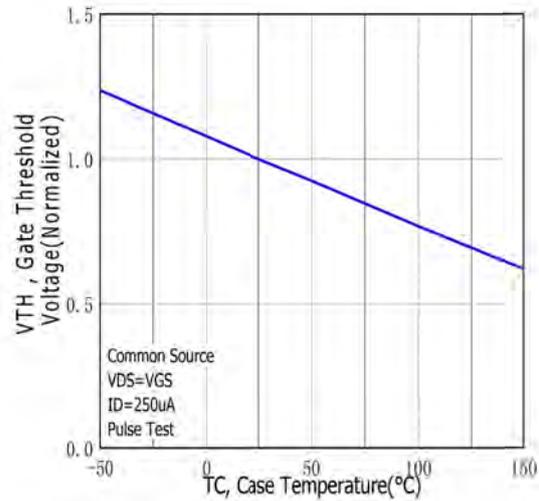
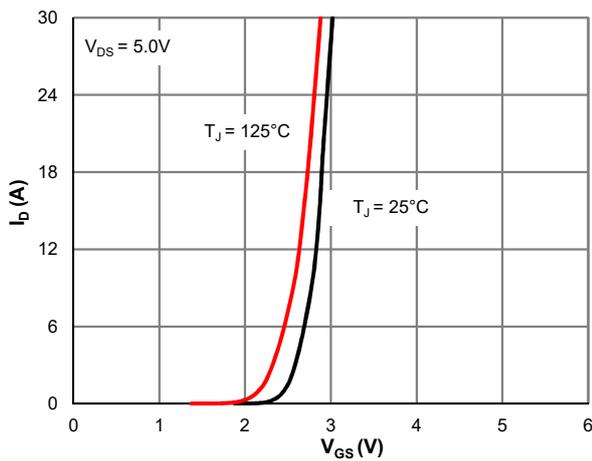
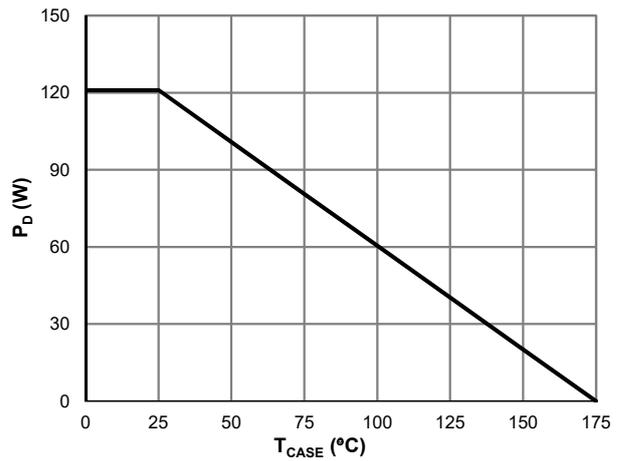


Figure.10 Typical Threshold Voltage vs Case Temperature



Transfer Characteristics

Figure.11 Typical Transfer Characteristics

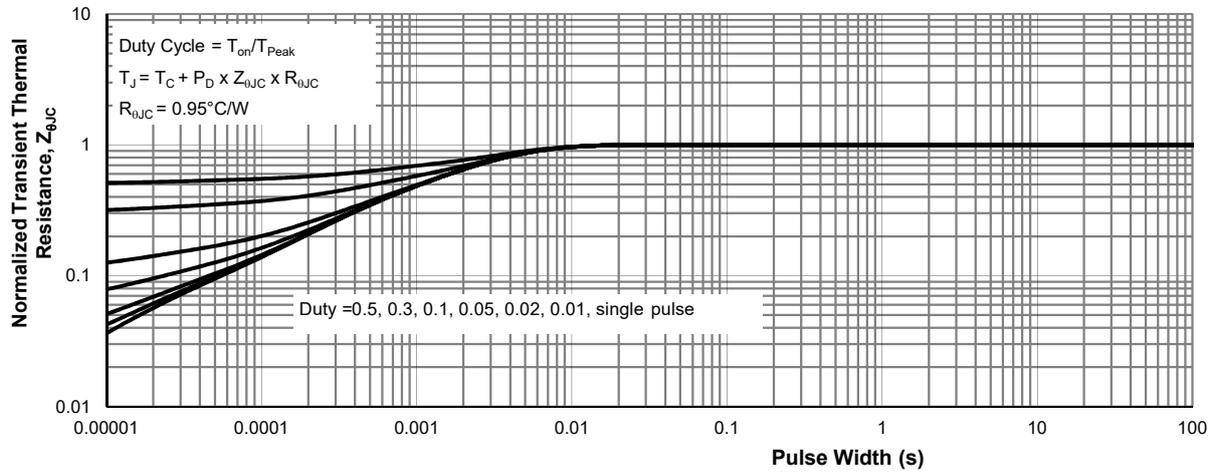


Power De-rating

Figure.12 Maximum Power Dissipation vs Case Temperature

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## N Channel Power MOSFETs



Normalized Maximum Transient Thermal Impedance

Figure.13 Maximum Effective Thermal Impedance , Junction to Case